



Material Content Data Sheet



Sales Product Name		BFP 181 E7764		Issued		27. September 2017		
MA#		MA000770690						
Package		PG-SOT143-4-1		Weight*		11.06 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.002	0.02		163	
	non noble metal	tin	7440-31-5	0.000	0.00		42	
	inorganic material	silicon	7440-21-3	0.013	0.12	0.14	1208	1413
leadframe	non noble metal	nickel	7440-02-0	1.673	15.12		151177	
	non noble metal	iron	7439-89-6	2.310	20.88	36.00	208769	359946
wire	noble metal	gold	7440-57-5	0.017	0.15	0.15	1547	1547
encapsulation	organic material	carbon black	1333-86-4	0.104	0.94		9438	
	inorganic material	antimonytrioxide	1309-64-4	0.157	1.42		14157	
	plastics	brominated resin	-	0.196	1.77		17696	
	plastics	epoxy resin	-	1.632	14.75		147465	
	inorganic material	silicondioxide	60676-86-0	4.438	40.11	58.99	401104	589860
leadfinish	non noble metal	tin	7440-31-5	0.219	1.98	1.98	19821	19821
plating	noble metal	silver	7440-22-4	0.303	2.74	2.74	27413	27413
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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